FAIRCHILD SEMICONDUCTOR®

December 2013

FQB8N90C

N-Channel QFET® MOSFET

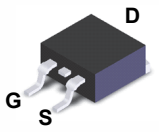
900 V, 6.3 A, 1.9 Ω

Description

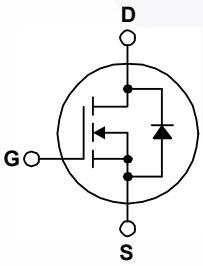
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.

Features

- 6.3 A, 900 V, $R_{DS(on)}$ = 1.9 Ω (Max.) @ V_{GS} = 10 V
- Low Gate Charge (Typ. 35 nC)
- Low C_{rss} (Typ. 12 pF)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability



D^2-PAK



Absolute Maximum Ratings

T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQB8N90CTM	Unit
V_{DSS}	Drain-Source Voltage		900	V
I_D	Drain Current - Continuous (T_C = 25°C)		6.3	A
	- Continuous (T_C = 100°C)		3.8	A
I_{DM}	Drain Current - Pulsed	(Note 1)	25	A
V_{GSS}	Gate-Source Voltage		± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	850	mJ
I_{AR}	Avalanche Current	(Note 1)	6.3	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	17.1	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.0	V/ns
P_D	Power Dissipation (T_C = 25°C)		171	W
	- Derate Above 25°C		1.37	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds.		300	°C

Thermal Characteristics

Symbol	Parameter	FQB8N90CTM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.73	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQB8N90CTM	FQB8N90C	D^2-PAK	Tape and Reel	330 mm	24 mm	800 untis

Electrical Characteristics

T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 μA	900	--	--	V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	--	0.95	--	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 900 V, V_{GS} = 0 V	--	--	10	μA
		V_{DS} = 720 V, T_C = 125°C	--	--	100	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 30 V, V_{DS} = 0 V	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30 V, V_{DS} = 0 V	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 μA	3.0	--	5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 3.15 A	--	1.6	1.9	Ω
g_{FS}	Forward Transconductance	V_{DS} = 50 V, I_D = 3.15 A	--	5.5	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	--	1600	2080	pF
C_{oss}	Output Capacitance		--	130	170	pF
C_{rss}	Reverse Transfer Capacitance		--	12	15	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 450 V, I_D = 8 A, V_{GS} = 10 V, R_G = 25 Ω (Note 4)	--	40	90	ns
t_r	Turn-On Rise Time		--	110	230	ns
$t_{d(off)}$	Turn-Off Delay Time		--	70	150	ns
t_f	Turn-Off Fall Time		--	70	150	ns
Q_g	Total Gate Charge	V_{DS} = 720 V, I_D = 8 A, V_{GS} = 10 V (Note 4)	--	35	45	nC
Q_{gs}	Gate-Source Charge		--	10	--	nC
Q_{gd}	Gate-Drain Charge		--	14	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	6.3	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	25	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 6.3 A	--	--	1.4	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_S = 8 A, dI_F / dt = 100 A/μs	--	530	--	ns
Q_{rr}	Reverse Recovery Charge		--	5.8	--	μC

Notes:

1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. L = 40 mH, I_{AS} = 6.3 A, V_{DD} = 50 V, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 8 A, di/dt ≤ 200 A/μs, V_{DD} ≤ BV_{DSS}, starting T_J = 25°C.
4. Essentially independent of operating temperature.

Typical Characteristics

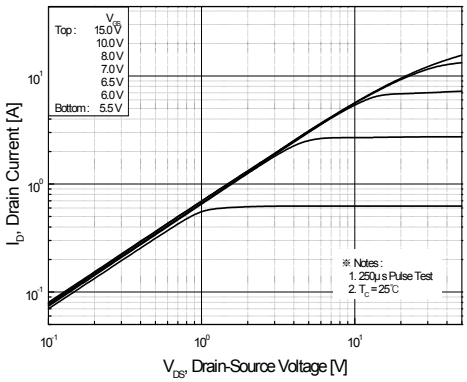


Figure 1. On-Region Characteristics

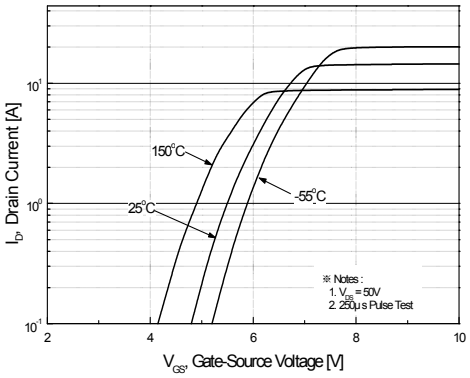


Figure 2. Transfer Characteristics

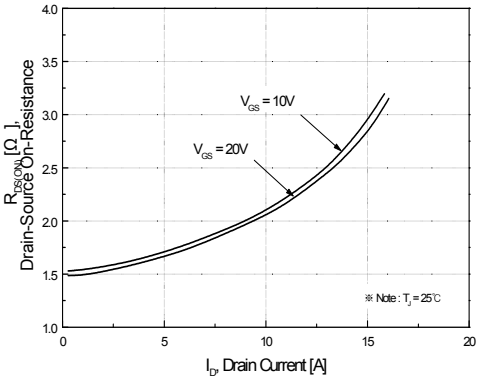


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

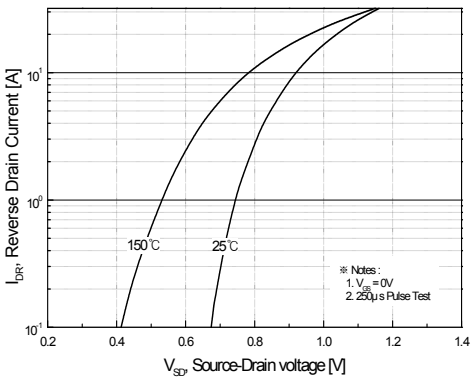


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

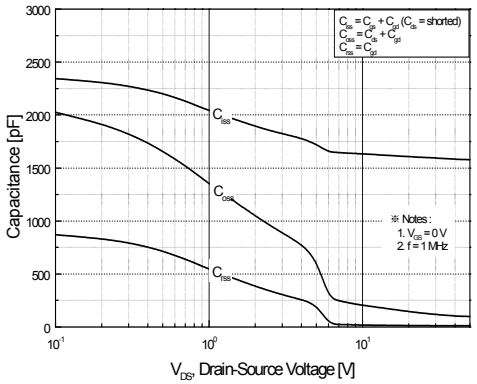


Figure 5. Capacitance Characteristics

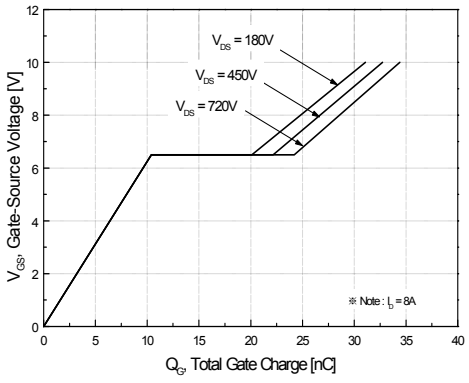


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

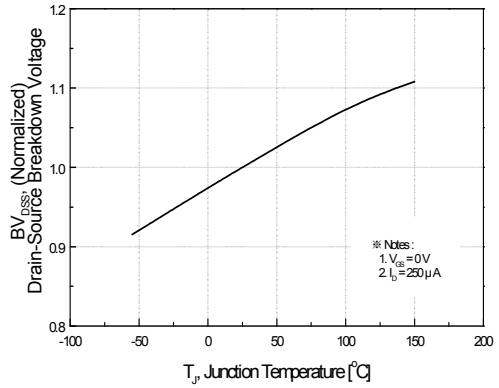


Figure 7. Breakdown Voltage Variation vs Temperature

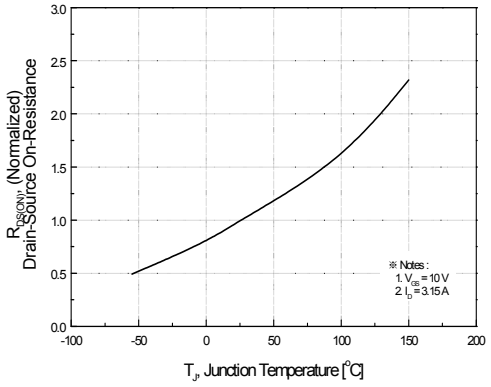


Figure 8. On-Resistance Variation vs Temperature

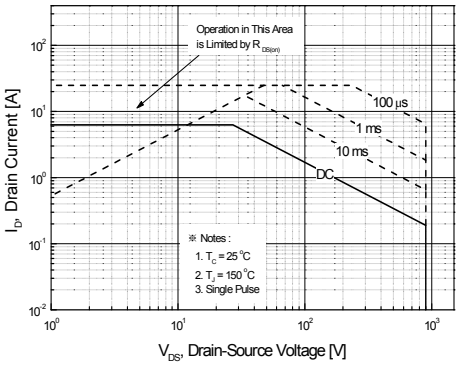


Figure 9. Maximum Safe Operating Area

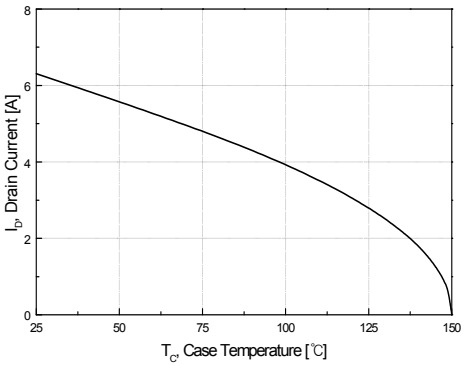


Figure 10. Maximum Drain Current vs Case Temperature

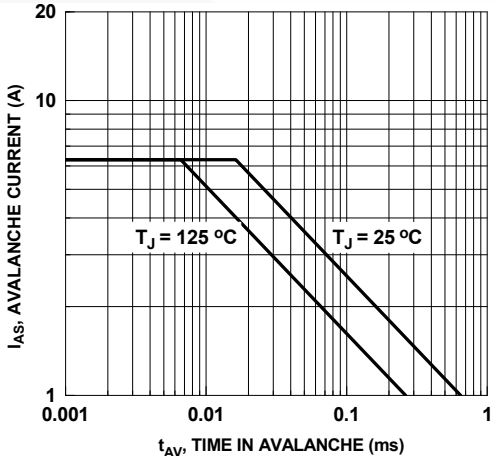


Figure 11. Unclamped Inductive Switching Capability

Typical Characteristics (Continued)

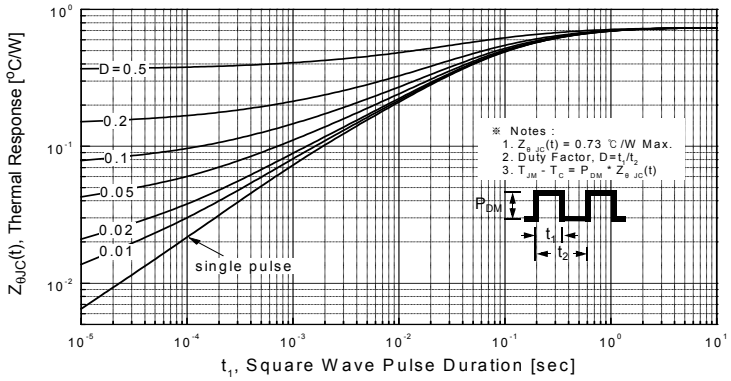


Figure 12. Transient Thermal Response Curve

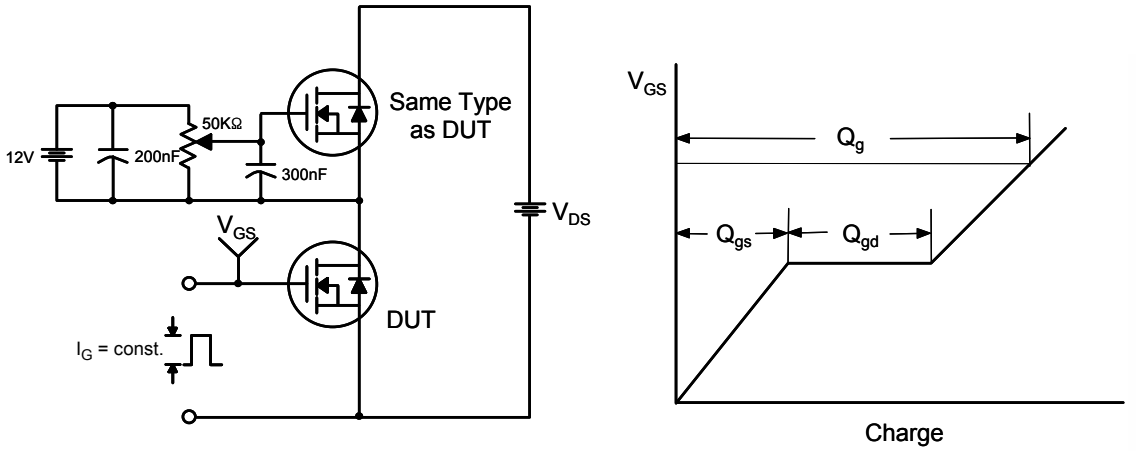


Figure 13. Gate Charge Test Circuit & Waveform

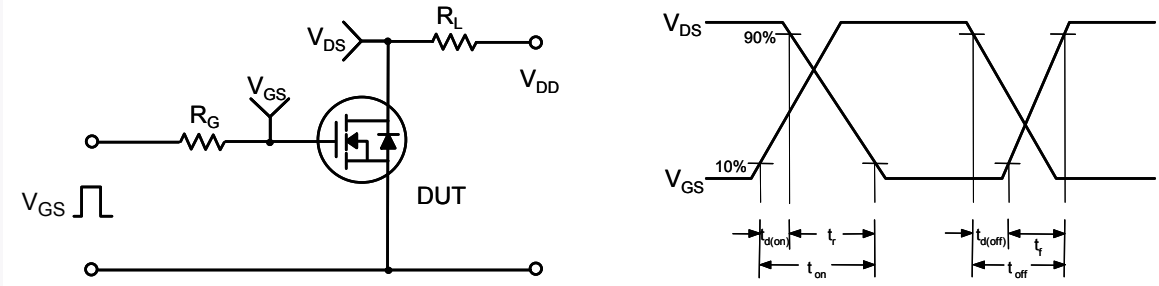


Figure 14. Resistive Switching Test Circuit & Waveforms

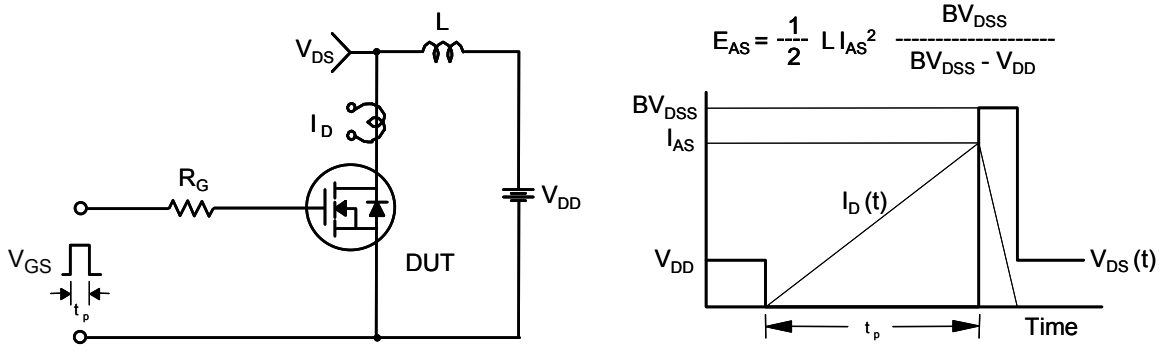


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

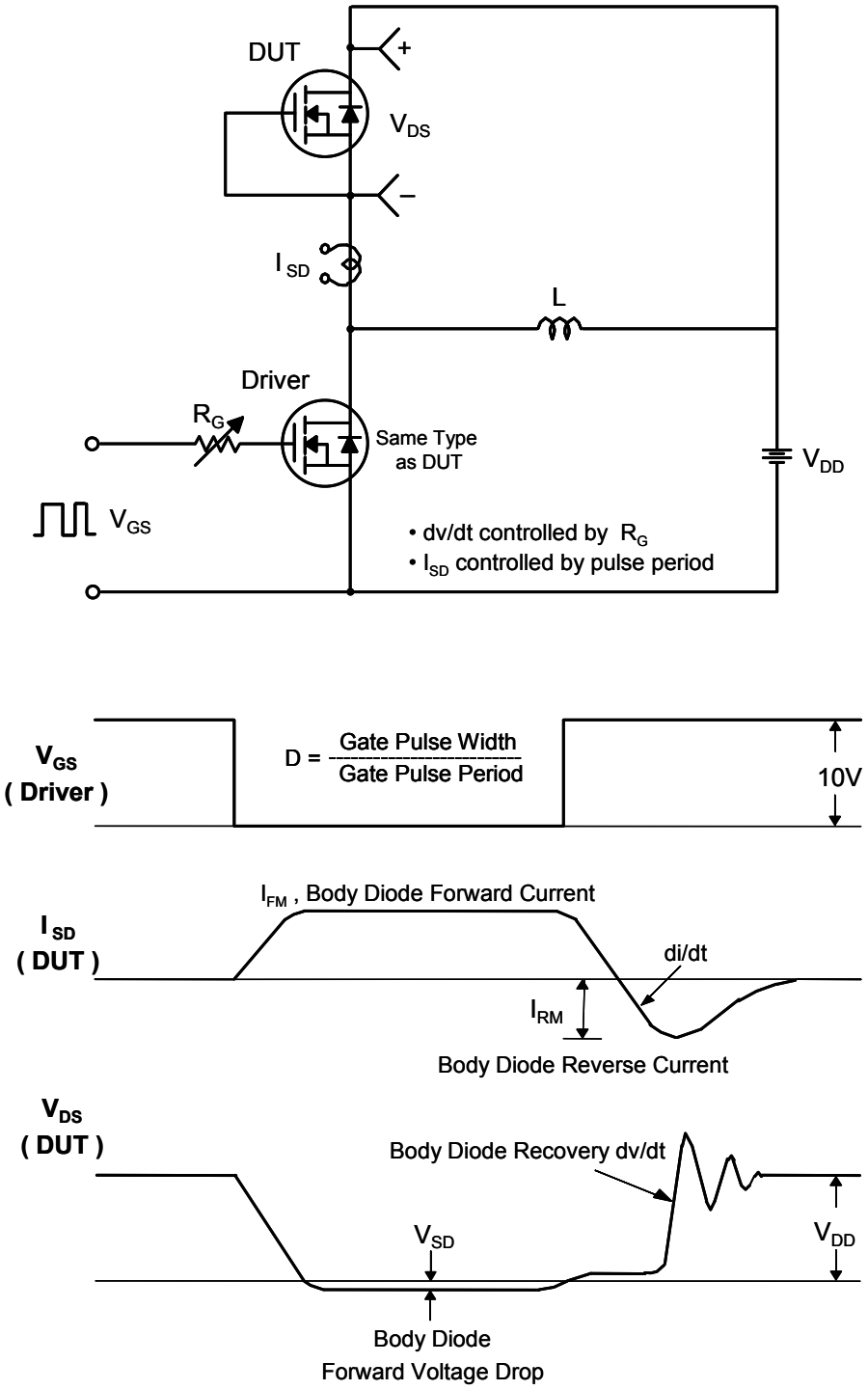


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

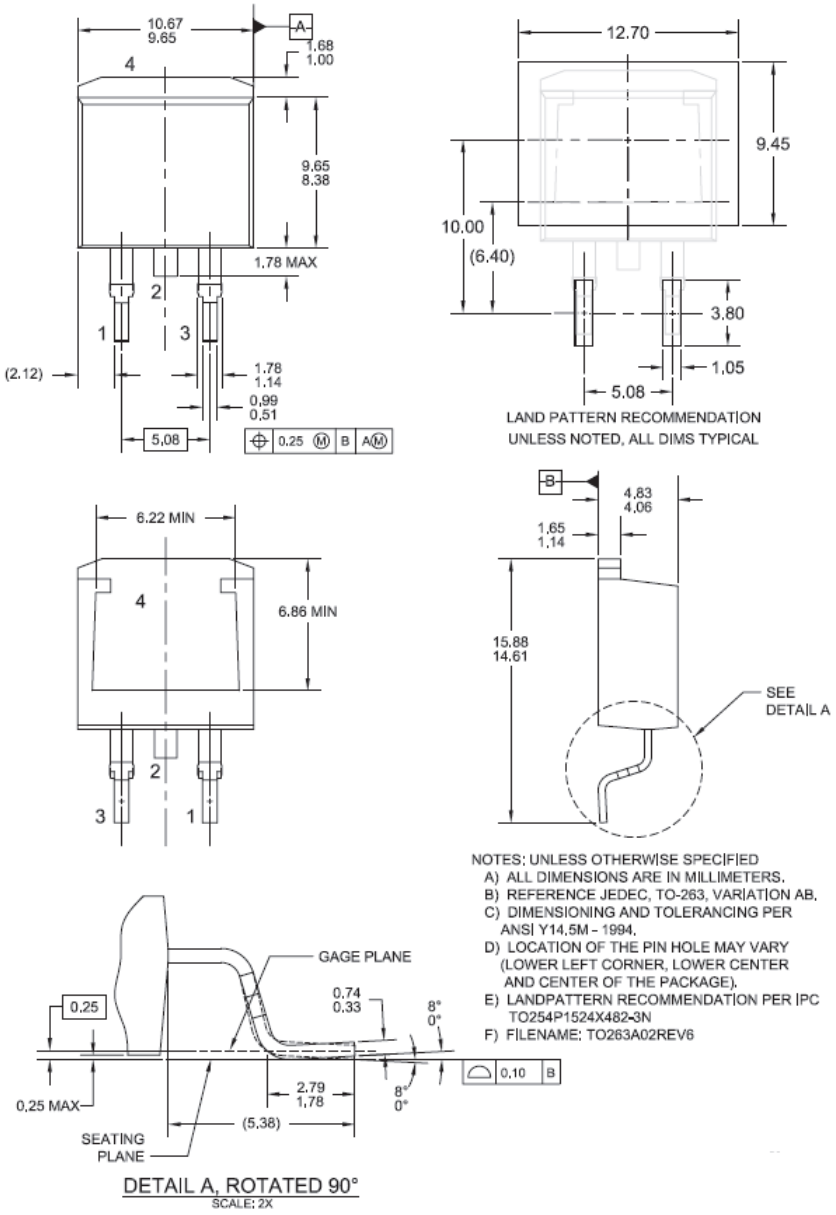


Figure 17. TO263 (D^2PAK), Molded, 2-Lead, Surface Mount

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